ASSOCIATION CONNECT: ELECTRONICS INDUSTR	Material Compo © Copyright 2005. IP international and Pan-	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard  Form Type http://www.ipc.org/IPC-175x  Form Type Distribute					* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
upplier Inform									,			<u>, , , , , , , , , , , , , , , , , , , </u>				
Company name* Company unique ID					Unique ID Authority				Response Date*							
nsemi											2024-05	2024-05-16				
Contact Name Title - Contact				ct	Phone - Co			ontact*			Email - Contact*					
Product-Env-Stewards Pro				Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - R				Representative			Phone - Representative*			Email - Representative*						
Product-Env-Stewards Product Enviro Compliance						NA				Product-Env-Stewards@onsemi.com						
Reques	ster Item Number	Mfr Item	Number	Mfr Item Name			Effective Date		n I	Manufacturing Site		Weight*	UOM	Unit Type		
		AP0201A A0-TR	AT2L00XEG	2MP CO-PROCE	SSOR		2024-05-16		1	MY5		91.24	mg	Each		
<b>Lanufacturing</b>	g Proccess Informati	ion														
Terminal Plating / Grid Array Material Terminal Base			Alloy	-STD-020 MS	-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow						per of Reflow Cyc	eles				
SnAgCu		C	CU Alloy 3			260	60 C 30		secon	nds 3						
omments	<u> </u>											·	<u> </u>			
TTENTION: MS	SL 3 Rated item requires	Bake and D	ry Pack (after	electrical test)												
or more informat	tion regarding material c	omposition 1	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	8.58	mg		Misc.	proprietary data		0.0249	mg
			Supplier	Silicon (Si)	7440-21-3		8.5465	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0086	mg
Die Attach Epoxy	0.9	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.009	mg
			Supplier	Filler (SiO2)	68909-20-6		0.36	mg
			Supplier	3-Methacryloxypropyltrimethoxysilane (C10H20O5Si)	2530-85-0		0.009	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.162	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.36	mg
Mold Compound-Black	33.58	mg		Epoxy resin	proprietary data		1.5111	mg
			Supplier	Phenolic Resin	Proprietary Data		1.5111	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1007	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		30.4571	mg
Solder Ball	10.5	mg	Supplier	Silver (Ag)	7440-22-4		0.315	mg
			Supplier	Tin (Sn)	7440-31-5		10.1325	mg
			Supplier	Copper (Cu)	7440-50-8		0.0525	mg
Substrate	20.0	mg		Epoxy resin	proprietary data		2.94	mg
			Supplier	Boehmit (Al(OH)O)	1318-23-6		6.1	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		4.6	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.36	mg
			Supplier	Misc.	Proprietary Data		1.7	mg
			Supplier	Polycarbonite	80-05-7		0.2	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		4.1	mg
Substrate and Solder Mask	2.48	mg	Supplier	Talc	14807-96-6		0.0893	mg
			Supplier	Epoxy Resin	26875-67-2		1.5277	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0248	mg
			Supplier	Misc.	Proprietary Data		0.067	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		0.7713	mg
Substrate Copper Foil	8.66	mg	Supplier	Copper (Cu)	7440-50-8		8.66	mg
Substrate Plating-Au	1.18	mg	Supplier	Gold (Au)	7440-57-5		1.18	mg
Substrate Plating-Cu	1.05	mg	Supplier	Copper (Cu)	7440-50-8		1.05	mg
Substrate Plating-Ni	3.36	mg	В	Nickel (Ni)	7440-02-0		3.36	mg

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Wire Bond - Au	0.95	mg	Supplier	Gold (Au)	7440-57-5	0.95	mg
Wife Bolla - Au	10.33	ing	Supplier	[Cold (Au)	/ <del>++</del> 0-3/-3	0.23	ing